

**DECLARATION AND POWER OF ATTORNEY FOR PATENT APPLICATION**DOCKET NO. TS03-299

As a below named Inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name;

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled  
Copper Cmp Defect Reduction By Extra Slurry Polish

the specification of which (check one)

X is attached hereto.

was filed on \_\_\_\_\_

Application Serial No. \_\_\_\_\_

and was amended on \_\_\_\_\_ (if applicable)

I hereby state that I have reviewed and understand the contents of the above Identified specification including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information which is material to the examination of this application in accordance with Title 37, Code of Federal Regulations, §1.56(a).

I hereby claim foreign priority benefits under Title 35, United States Code §119 of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

Prior Foreign Application(s)

Priority Claimed:

(Number)	(Country)	(Day/Month/Year Filed)
(Number)	(Country)	(Day/Month/Year Filed)

I hereby claim the benefit under Title 35, United States Code §120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, §112, I acknowledge the duty to disclose material information as defined in Title 37, Code of Federal Regulations, §1.56(a) which occurred between the filing date of the prior application and the national or PCT international filing date of this application:

(Application Serial No.)	(Filing Date)	(Status) (patented, pending, abandoned)
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I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

**POWER OF ATTORNEY:** As a named inventor, I hereby appoint the following attorney(s) and/or agent(s) to prosecute this application and transact all business in the Patent and Trademark Office connected therewith. (list name & registration no.)

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Full name of sole or first inventor

10/28/2003

Date

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DOCKET NO. TS03-299

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10/28/03

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SYUN-MING JANG

Full name of sixth inventor

Syun-Ming Jang

Date

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Post Office Address

and which is found in

- (a)  U.S. patent application executed on even date herewith
- (b)  U.S. patent application executed on \_\_\_\_\_
- (c)  U.S. application serial no. \_\_\_\_\_ filed on \_\_\_\_\_
- (d)  U.S. patent no. \_\_\_\_\_ issued \_\_\_\_\_  
(also check (e) if foreign application(s) is also being assigned)
- (e)  and any legal equivalent thereof in a foreign country, including the right to claim priority

and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuation, division, renewal, or substitute, thereof, and as to letters patent any re-issue or re-examination thereof.

ASSIGNOR hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment.

ASSIGNOR further covenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to ASSIGNOR and will testify as to the same in any interference, litigation or proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the purposes thereof.

IN WITNESS WHEREOF, I / We have signed this

10/28/2003 (Date of signing)

WARNING Date of signing must be the same as the date of execution of the application if item (a) was checked above.

William Wong  
Signature of ASSIGNOR(S)  
Chia-Che Chuang  
Chi-Wei Chung  
Wen-Chih Chou

If ASSIGNOR is a legal entity complete the following information

\_\_\_\_\_  
Type or print the name of the above person authorized to sign on  
behalf of ASSIGNOR

\_\_\_\_\_  
Title

Note: No witnessing, notarization or legalization is necessary, if the assignment is notarized or legalized then it will only be prima facie evidence (35 USC 261). Use next page if notarization is desired.

\_\_\_\_\_  
Notarization or Legalization Page Added.

and which is found in

(a)  U.S. patent application executed on even date herewith

(b)  U.S. patent application executed on \_\_\_\_\_

(c)  U.S. application serial no. \_\_\_\_\_ filed on \_\_\_\_\_

(d)  U.S. patent no. \_\_\_\_\_ issued \_\_\_\_\_  
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IN WITNESS WHEREOF, I / We have signed this

10/28/2003 (Date of signing)

**WARNING:** Date of signing must be the same as the date of execution of the application if item (a) was checked above.

Ying-Ho Chen  
Signature of ASSIGNOR(S)

If ASSIGNEE is a legal entity complete the following information

Type or print the name of the above person authorized to sign on behalf of ASSIGNOR

**Title**

Note: No witnessing, notarization or legalization is necessary, if the assignment is notarized or legalized then it will only be *prima facie* evidence (35 USC 261). Use next page if notarization is desired.

Notarization or Legalization Page Added.